



N- and P-Channel 20 V (D-S) MOSFET

| PRODUCT SUMMARY | | | | | | | | |
|-----------------|---------------------------------|--------------------------------------|-------|--------|--|--|--|--|
| | I _D (A) ^a | Q _g (Typ.) | | | | | | |
| N-Channel | 20 | 0.058 at $V_{GS} = 4.5 \text{ V}$ | 3.9 | 2.9 nC | | | | |
| | | 0.078 at $V_{GS} = 2.5 \text{ V}$ | 3.3 | 2.9110 | | | | |
| P-Channel | hannel - 20 | 0.195 at $V_{GS} = -4.5 \text{ V}$ | - 2.1 | 1.6 nC | | | | |
| r-Chainei | | 0.316 at $V_{GS} = -2.5 \text{ V}$ | - 1.7 | 1.0110 | | | | |

FEATURES

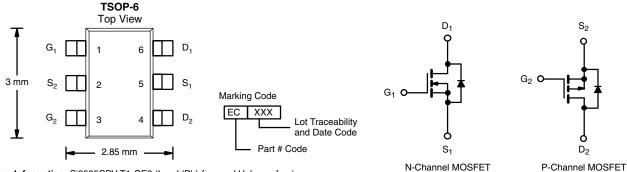
- TrenchFET® Power MOSFETs
- 100 % R_g Tested
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912



COMPLIANT HALOGEN FREE

APPLICATIONS

- Load Switch for Portable Devices
- DC/DC Converters
- Drivers: Motor, Solenoid, Relay



Ordering Information: Si3585CDV-T1-GE3 (Lead (Pb)-free and Halogen-free)

| ABSOLUTE MAXIMUM RATING | \mathbf{S} (1 _A = 25 °C, unle | ess otnerwise | e notea) | | | |
|--|--|----------------|---------------------|-----------------------|-----|--|
| Parameter | Symbol | N-Channel | P-Channel | Unit | | |
| Drain-Source Voltage | V_{DS} | 20 | - 20 | V | | |
| Gate-Source Voltage | | V_{GS} | ± | V | | |
| | T _C = 25 °C | | 3.9 | - 2.1 | | |
| Ocations on Durin Oceanal (T., 450.00) | T _C = 70 °C | , | 3.1 | - 1.7 | | |
| Continuous Drain Current (T _J = 150 °C) | T _A = 25 °C | l _D | 3.5 ^{b, c} | - 1.9 ^{b, c} | А | |
| | T _A = 70 °C | | 2.8 ^{b, c} | - 1.5 ^{b, c} | | |
| Pulsed Drain Current (t = 300 μs) | I _{DM} | 12 | - 5 | | | |
| Course Dunin Coursent Diada Coursent | T _C = 25 °C | | 1.2 | - 1.1 | | |
| Source Drain Current Diode Current | T _A = 25 °C | I _S | 0.9 ^{b, c} | - 0.9 ^{b, c} | | |
| | T _C = 25 °C | | 1.4 | 1.3 | | |
| Mandagora Barras Biochaethau | T _C = 70 °C | | 0.9 | 0.8 | 147 | |
| Maximum Power Dissipation | T _A = 25 °C | P _D | 1.1 ^{b, c} | 1.1 ^{b, c} | W | |
| | T _A = 70 °C | | 0.7 ^{b, c} | 0.7 ^{b, c} | | |
| Operating Junction and Storage Temperature R | T _J , T _{sta} | - 55 t | o 150 | °C | | |

| THERMAL RESISTANCE RATINGS | | | | | | | | |
|---|--------------|-------------------|------|-----------|------|------|--------------|--|
| Parameter | Symbol | N-Channel | | P-Channel | | Unit | | |
| Parameter | | Syllibol | Тур. | Max. | Тур. | Max. | Ollit | |
| Maximum Junction-to-Ambient ^{b, d} t ≤ 5 s | | R _{thJA} | 93 | 110 | 97 | 115 | °C/W | |
| Maximum Junction-to-Foot (Drain) | Steady State | R_{thJF} | 75 | 90 | 78 | 95 | O/ VV | |

Notes:

- a. Based on $T_C = 25$ °C.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 5 s.
- d. Maximum under steady state conditions is 150 °C/W for n-channel and 155 °C/W for p-channel.

Si3585CDV

Vishay Siliconix



| Parameter | Test Conditions | Min. | Тур. Мах. | | Unit | | | |
|---|-------------------------|---|--------------|----------|--------|---------|-------|--|
| Static | Symbol | | | | .,,,, | 1110221 | | |
| | | V _{GS} = 0 V, I _D = 250 μA | N-Ch | 20 | | 1 | | |
| Drain-Source Breakdown Voltage | V_{DS} | $V_{GS} = 0 \text{ V, } I_{D} = -250 \mu\text{A}$ | P-Ch | - 20 | | | V | |
| | | I _D = 250 μA | | | 15 | | | |
| V _{DS} Temperature Coefficient | $\Delta V_{DS}/T_{J}$ | I _D = - 250 μA | P-Ch | | - 16.2 | | mV/°C | |
| | | I _D = 250 μA | N-Ch | | - 2.8 | | | |
| V _{GS(th)} Temperature Coefficient | $\Delta V_{GS(th)}/T_J$ | I _D = - 250 μA | P-Ch | | 2.5 | | | |
| | ., | $V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$ | N-Ch | 0.6 | | 1.5 | V | |
| Gate Threshold Voltage | V _{GS(th)} | V _{DS} = V _{GS} , I _D = - 250 μA | P-Ch | - 0.6 | | - 1.5 | | |
| Oata Oarma Laskana | 1 | V 0VV .10V | N-Ch | | | ± 100 | ^ | |
| Gate-Source Leakage | I _{GSS} | $V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$ | P-Ch | | | ± 100 | nA | |
| | | V _{DS} = 20 V, V _{GS} = 0 V | N-Ch | | | 1 | | |
| Zana Oata Vallana Busin Oursel | | V _{DS} = - 20 V, V _{GS} = 0 V | P-Ch | | | - 1 | | |
| Zero Gate Voltage Drain Current | IDSS | V _{DS} = 20 V, V _{GS} = 0 V, T _J = 55 °C | N-Ch | | | 10 | - μΑ | |
| | | V _{DS} = - 20 V, V _{GS} = 0 V, T _J = 55 °C | P-Ch | | | - 10 | | |
| On-State Drain Current ^b | I _{D(on)} | $V_{DS} \ge 5 \text{ V}, V_{GS} = 4.5 \text{ V}$ | N-Ch | 12 | | | Α | |
| | | $V_{DS} \le -5 \text{ V}, V_{GS} = -4.5 \text{ V}$ | P-Ch | - 5 | | | | |
| Drain-Source On-State Resistance ^b | R _{DS(on)} | $V_{GS} = 4.5 \text{ V}, I_D = 2.5 \text{ A}$ | N-Ch | | 0.048 | 0.058 | Ω | |
| | | V _{GS} = - 4.5 V, I _D = - 1.9 A | P-Ch | | 0.162 | 0.195 | | |
| | | $V_{GS} = 2.5 \text{ V}, I_D = 1 \text{ A}$ | N-Ch | | 0.065 | 0.078 | | |
| | | V _{GS} = - 2.5 V, I _D = - 1 A | P-Ch | | 0.263 | 0.316 | | |
| b | _ | V _{DS} = 10 V, I _D = 35 A | N-Ch | | 12 | | S | |
| Forward Transconductance ^b | g _{fs} | V _{DS} = - 10 V, I _D = - 1.9 A | P-Ch | | 1 | | | |
| Dynamic ^a | • | | | <u> </u> | | | | |
| - | | | N-Ch | | 150 | | | |
| Input Capacitance | C _{iss} | N-Channel | P-Ch | | 210 | | - pF | |
| Output Capacitance | C _{oss} | $V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$ | N-Ch | | 53 | | | |
| - Carpat Capacitarios | -055 | P-Channel | P-Ch | | 50 | | | |
| Reverse Transfer Capacitance | C _{rss} | $V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$ | N-Ch | | 22 | | | |
| | 100 | | P-Ch | | 35 | | | |
| | | $V_{DS} = 10 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 3.5 \text{ A}$ | N-Ch | | 3.2 | 4.8 | nC | |
| Total Gate Charge | Q_g | $V_{DS} = -10 \text{ V}, V_{GS} = -10 \text{ V}, I_{D} = -1.9 \text{ A}$ | P-Ch | | 6 | 9 | | |
| | | N-Channel | N-Ch | | 1.6 | 2.4 | | |
| | | $V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 3.5 \text{ A}$ | P-Ch | | 2.9 | 4.3 | | |
| Gate-Source Charge | Q_{gs} | 30 7 GO 7 B | N-Ch | | 0.3 | | | |
| | Q _{gd} | P-Channel | P-Ch N-Ch | | 0.6 | | | |
| Gate-Drain Charge | | $V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -1.9 \text{ A}$ | | | 0.4 | | - | |
| | R _g | f = 1 MHz | | 0.0 | 0.9 | 0.6 | | |
| Gate Resistance | | | | 0.9 | 4.8 | 9.6 | Ω | |
| | | | | 1.2 | 6.2 | 12.4 | | |



| Parameter Symbol | | Test Conditions | Min. | Тур. | Max. | Unit | |
|--|---------------------|--|--------------|------|----------|----------|-------------|
| Dynamic ^a | | | | | | | |
| Turn-On Delay Time | t _{d(on)} | N. Ohannad | N-Ch | | 5 | 10 | |
| Tam on Boldy Time | -u(on) | N-Channel $V_{DD} = 10 \text{ V, } R_{L} = 3.6 \Omega$ | P-Ch | | 3 | 6 | |
| Rise Time | t _r | $I_D \cong 2.8 \text{ A, V}_{GEN} = 10 \text{ V, R}_q = 1 \Omega$ | N-Ch | | 20 | 30 |] |
| | ' | | P-Ch | | 10 | 20 | |
| Turn-Off Delay Time | t _{d(off)} | P-Channel | N-Ch | | 11 | 20 | |
| | 4(0.1) | V_{DD} = - 10 V, R_L = 6.7 Ω | P-Ch | | 13 | 20 | |
| Fall Time | t _f | $I_D \cong$ - 1.5 A, V_{GEN} = - 10 V, R_g = 1 Ω | N-Ch | | 8 | 16 | |
| | | | P-Ch | | 7 | 14 | ns |
| Turn-On Delay Time | t _{d(on)} | N-Channel | N-Ch | | 15 | 23 | - |
| | =(=, | $V_{DD} = 10 \text{ V}, R_L = 3.6 \Omega$ | P-Ch N-Ch | | 16 | 25 | |
| Rise Time | t _r | $I_D \cong 2.8 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$ | P-Ch | | 37 16 | 56 25 | |
| | | | N-Ch | | 25 | 38 | |
| Turn-Off Delay Time | t _{d(off)} | P-Channel | P-Ch | | 13 | 20 | - - - |
| | | $V_{DD} = -10 \text{ V}, R_L = 6.7 \Omega$ $I_D \cong -1.5 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_q = 1 \Omega$ | N-Ch | | 28 | 42 | |
| Fall Time | t _f | ID = 1.5 A, VGEN = 14.5 V, Hg = 132 | P-Ch | | 9 | 18 | |
| Drain-Source Body Diode Characteristi | cs | | | | | | |
| Continuous Course Dunis Diede Courset | I _S | T _C = 25 °C | N-Ch | | | 1.2 | |
| Continuous Source-Drain Diode Current | | 1 _C = 25 C | P-Ch | | | - 1.1 | |
| Pulse Diode Forward Current ^a | I _{SM} | | N-Ch | | | 12 | Α |
| Pulse Diode Forward Current | ISM | | P-Ch | | | - 5 | |
| Body Diode Voltage | V _{SD} | $I_S = 2.8 \text{ A}, V_{GS} = 0 \text{ V}$ | N-Ch | | 0.8 | 1.2 | V |
| Body Blode Voltage | | I _S = - 1.5 A, V _{GS} = 0 V | P-Ch | | - 0.8 | - 1.2 | V |
| Rady Diada Dayaraa Daasyary Tima | + | | N-Ch | | 8 | 16 | |
| Body Diode Reverse Recovery Time | t _{rr} | | P-Ch | | 21 | 32 | ns |
| Body Diode Reverse Recovery Charge | Q _{rr} | N-Channel | N-Ch | | 2 | 4 | nC |
| Body Blode Heverse Hecovery Charge | | $I_F = 2.8 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$ | P-Ch | | 11 | 20 | 110 |
| Reverse Recovery Fall Time | t _a | P-Channel | N-Ch | | 5 | | |
| 1.0. o. | | $I_F = -1.5 \text{ A}, \text{ dI/dt} = -100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$ | P-Ch | | 10 | | ns |
| Reverse Recovery Rise Time | t _b | | N-Ch | | 3 | | 110 |
| | ď. | | P-Ch | | 11 | | |

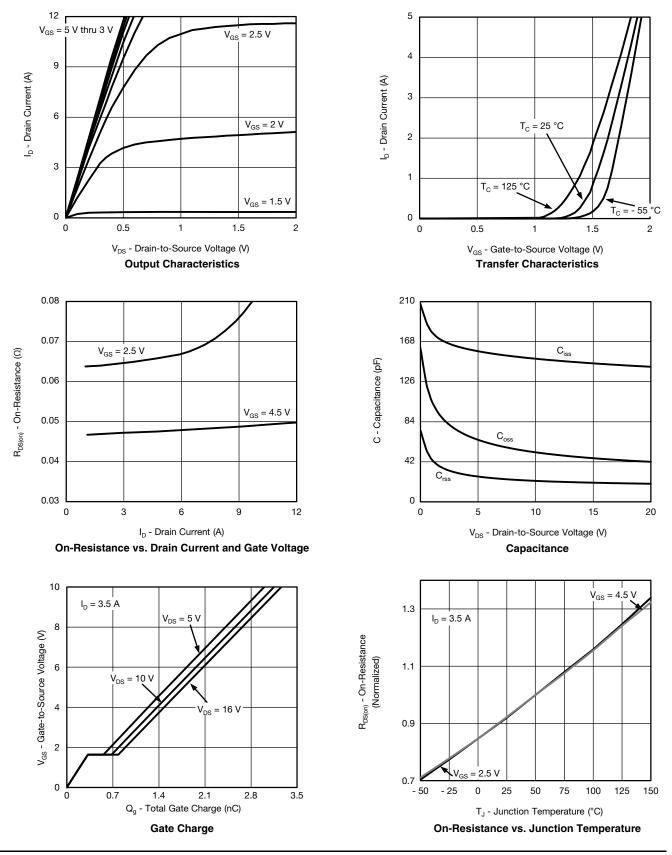
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Guaranteed by design, not subject to production testing.

b. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$

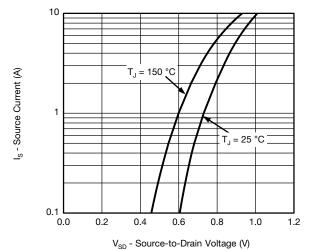
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N-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

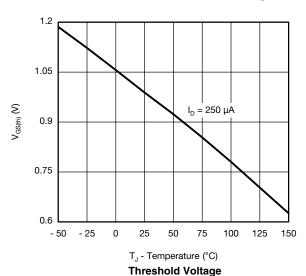




N-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



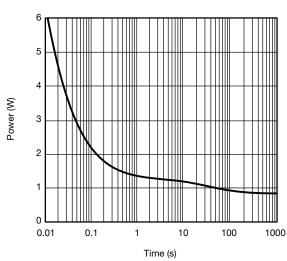
Source-Drain Diode Forward Voltage



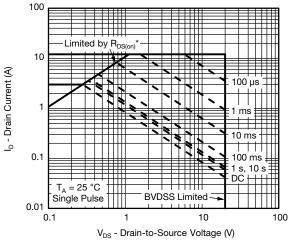
 $C_{\text{D}} = 3.5 \text{ A}$ $C_{\text{D}} = 3.5 \text{ A}$

V_{GS} - Gate-to-Source Voltage (V)

On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power

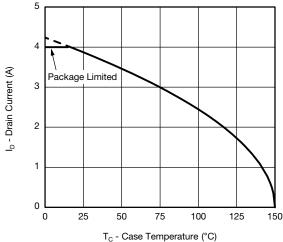


* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

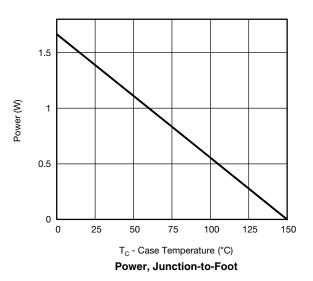
Safe Operating Area, Junction-to-Ambient

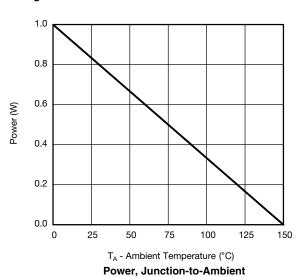


N-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Current Derating*

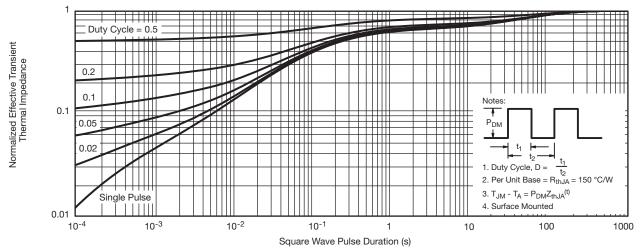




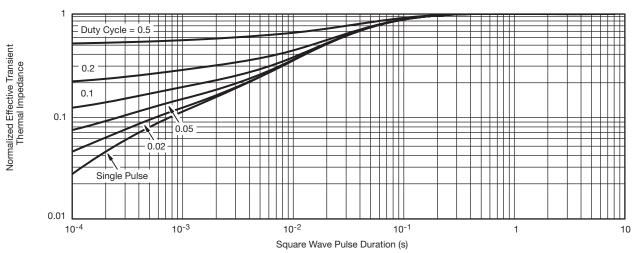
^{*} The power dissipation P_D is based on $T_{J(max.)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



N-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

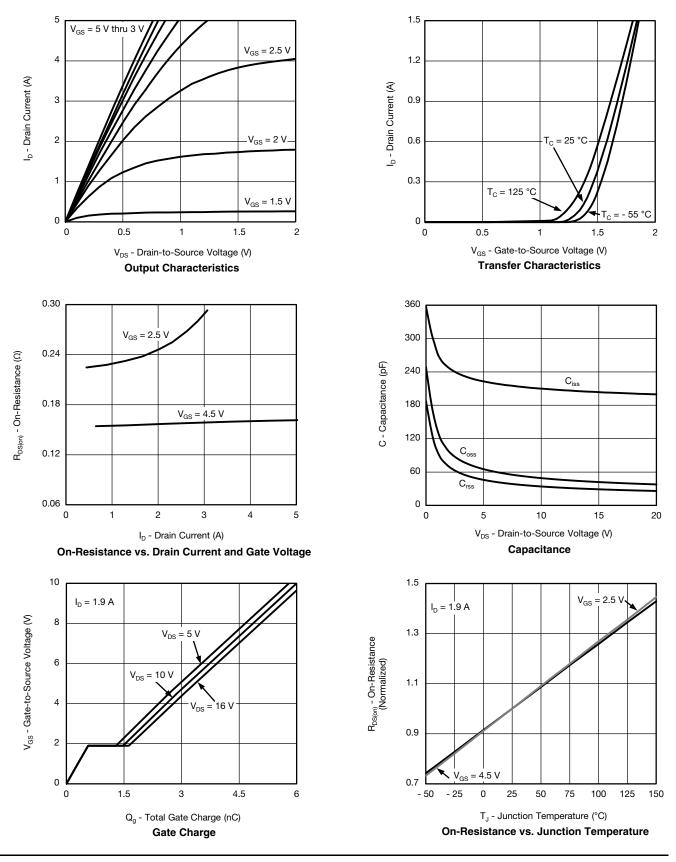


Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

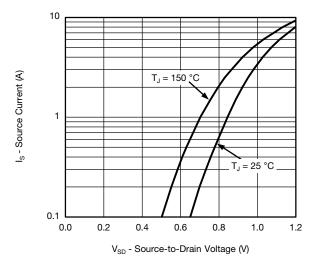
P-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

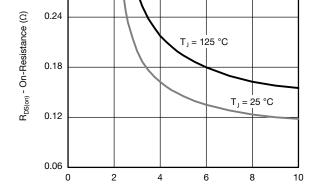


 $I_{D} = 1.9 A$



P-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

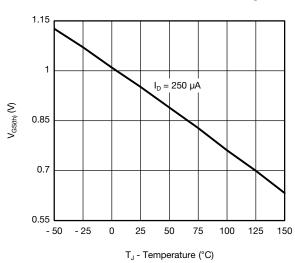




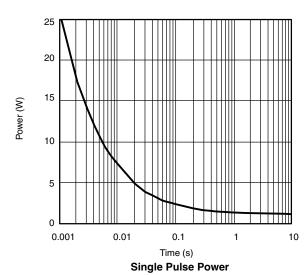
0.3

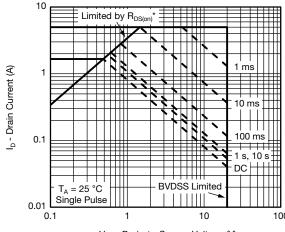
Source-Drain Diode Forward Voltage

V_{GS} - Gate-to-Source Voltage (V) On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



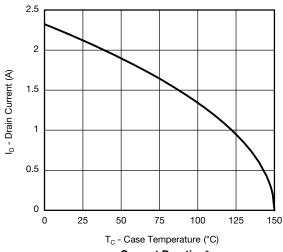


V_{DS} - Drain-to-Source Voltage (V) * V_{GS} > minimum V_{GS} at which $R_{\text{DS(on)}}$ is specified Safe Operating Area, Junction-to-Ambient

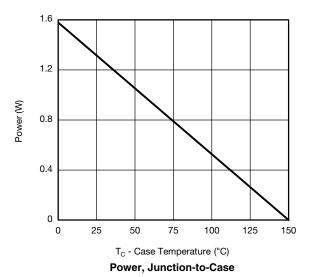
Document Number: 67470 S13-1562-Rev. C, 15-Jul-13

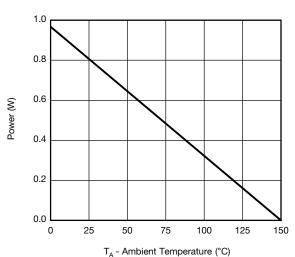


P-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Current Derating*



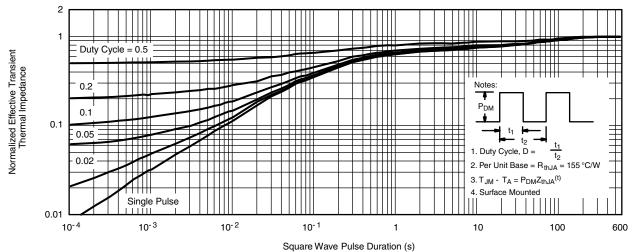


Power, Junction-to-Ambient

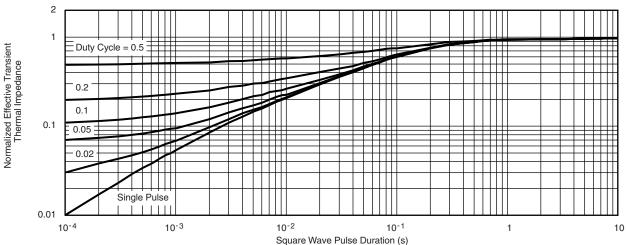
^{*} The power dissipation P_D is based on $T_{J(max.)}$ = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



P-CHANNEL TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

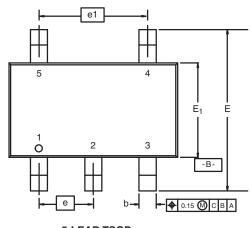
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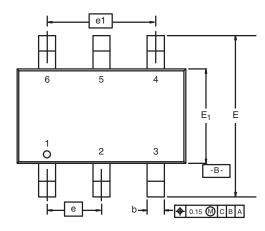




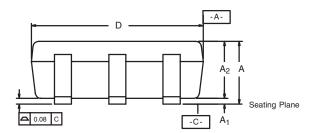
TSOP: 5/6-LEAD

JEDEC Part Number: MO-193C

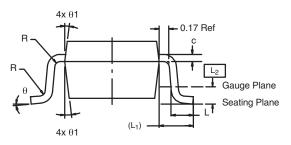




5-LEAD TSOP







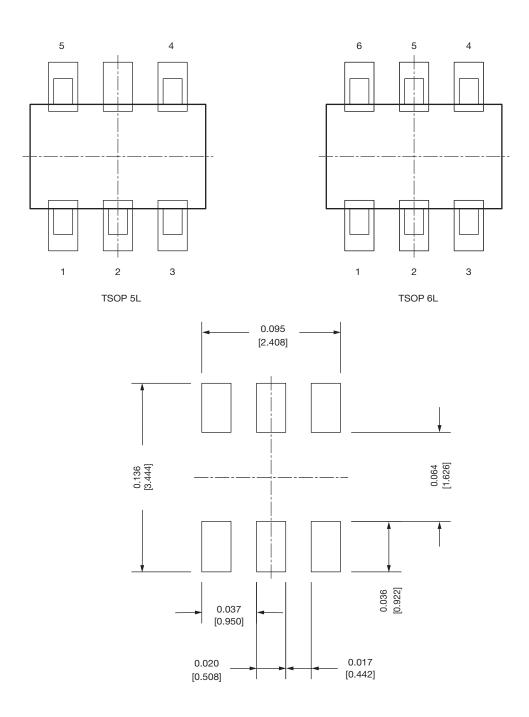
| | MIL | LIMETER | RS | ı | NCHES | | | |
|---|--------------------|----------|------|------------|-------|-------|--|--|
| Dim | Min | Nom | Max | Min | Nom | Max | | |
| Α | 0.91 | - | 1.10 | 0.036 | - | 0.043 | | |
| A ₁ | 0.01 | - | 0.10 | 0.0004 | - | 0.004 | | |
| A ₂ | 0.90 | - | 1.00 | 0.035 | 0.038 | 0.039 | | |
| b | 0.30 | 0.32 | 0.45 | 0.012 | 0.013 | 0.018 | | |
| С | 0.10 | 0.15 | 0.20 | 0.004 | 0.006 | 0.008 | | |
| D | 2.95 | 3.05 | 3.10 | 0.116 | 0.120 | 0.122 | | |
| E | 2.70 | 2.85 | 2.98 | 0.106 | 0.112 | 0.117 | | |
| E ₁ | 1.55 | 1.65 | 1.70 | 0.061 | 0.065 | 0.067 | | |
| е | | 0.95 BSC | | 0.0374 BSC | | | | |
| e ₁ | 1.80 | 1.90 | 2.00 | 0.071 | 0.075 | 0.079 | | |
| L | 0.32 | - | 0.50 | 0.012 | - | 0.020 | | |
| L ₁ | 0.60 Ref 0.024 Ref | | | | | | | |
| L ₂ | 0.25 BSC 0.010 BSC | | | | | | | |
| R | 0.10 | - | - | 0.004 | - | - | | |
| θ | 0° | 4° | 8° | 0° | 4° | 8° | | |
| θ_1 | 7° Nom 7° Nom | | | | | | | |
| ECN: C-06593-Rev. I, 18-Dec-06 DWG: 5540 | | | | | | | | |

Document Number: 71200

18-Dec-06



Recommended Land Pattern For TSOP-5L / TSOP-6L



Note

• All dimensions are in inches (millimeter)

ECN: C22-0860-Rev. B, 24-Oct-2022 DWG: 3010



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